



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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PRODUCT NUMBER
10075024-XXX-XXXLF

PLATING

S = 0.38µm GOLD ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL
G = 0.76µm GOLD ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL
F = GOLD FLASH ON CONTACT AREA
2µm MIN MATTE TIN ON TAIL

1.27µm MIN NICKEL UNDERPLATING

LEAD FREE
RoHS COMPATIBLE
NOTE 6

PACKAGING
NOTE 5

POSITIONS PER ROW
02 TO 25

SEE NOTE 9

PIN STYLE	DIM "A" ±0.25	DIM "B" ±0.20
01	4.00	2.00
02	6.90	2.00
03	5.80	2.00
04	6.00	3.00

NOTES:

- MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR BLACK
- MATERIAL TERMINAL: COPPER ALLOY
- TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
- 7N MIN. PIN RETENTION IN EITHER DIRECTION.
- PACKAGING:
= STANDARD PACKAGING IN POLYBAG
U = TUBE WITHOUT PICK UP CAP
AVAILABLE FROM 03 TO 25 POS PER ROW
P = TUBE WITH PICK UP CAP
AVAILABLE FROM 03 TO 25 POS PER ROW
A = TAPE AND REEL WITH PICK UP CAP, AS AVAILABLE.

6. RoHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:

- "LF" MEANS THE PRODUCT IS LEAD-FREE,
2µm MINIMUM MATTE TIN OVER 1.27µm
MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY

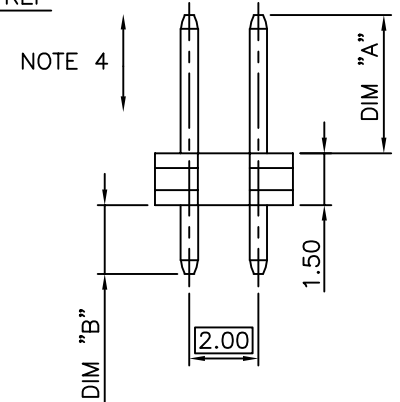
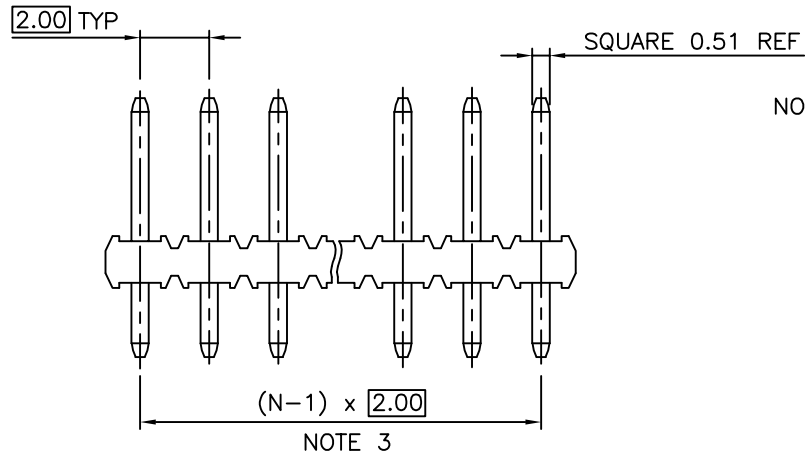
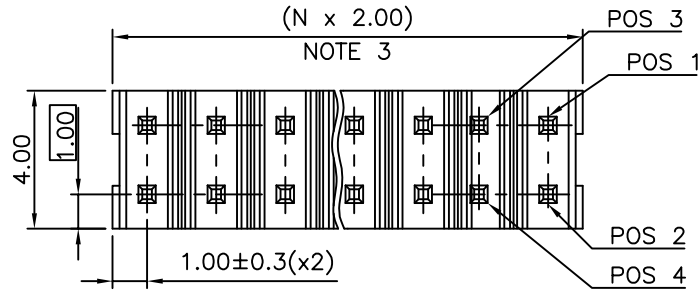
- THE HOUSING WILL WITHSTAND EXPOSURE TO
260°C PEAK TEMPERATURE FOR 30 SECONDS MAX
IN A CONVECTION, INFRA-RED, OR VAPOR PHASE
OR REFLOW OVEN

c - LABELLING:

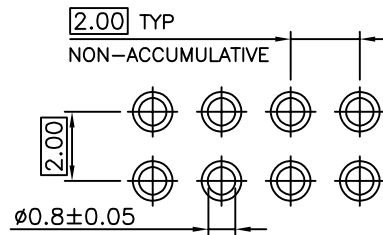
- MEETS PACKAGING SPECS AS PER GS-14-920
- LEGAL STATEMENT: SEE GS-47-0004

9. OPTIONAL LETTER:

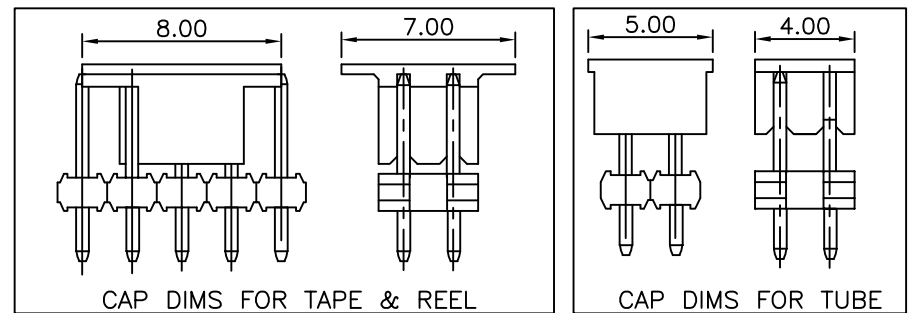
- FOR FULL LOADED PRODUCT USE -
- FOR POLARIZED VERSIONS, SEE TABLE



OPTIONAL LETTER FOR POLARIZED VERSION	MISSING PIN POSITION
A	20



RECOMMENDED 1.6mm THICK PCB LAYOUT
STENCIL DESIGN RECOMMENDATIONS



mat'l. code		surface		tolerance		projection		product family	
		ISO 1302		ISO 406 ISO 1101		mm		MINITEK	
ltr	ecn no	dr	date	tolerances unless otherwise specified		mm		title	
H	B-19797	AMA	14.12.16	angles	.x ±0.3	mm		UNSHR.HEADER	
J	F-23051	AMA	16.01.15	linear	.xx ±0.15	mm		2.00 mm VERTICAL PIP	
K	F-26013	DDE	17.02.02		.xxx ±0.05	scale 5:1		dwg no	
L	F-27930	DDE	17.09.11	dr	L MULIN 07.01.04	mm		sheet 1 of 1 size	
				enfr	J.COMPAGNON 07.01.04	mm		10075024 A3	
F	B-17556	JCO	14.04.23	chr		mm		type	
G	B-19190	LMU	14.10.24	appd	JM.C 07.01.04	mm		CUSTOMER Drawing	
sheet index	revision sheet								